



Printed Circuit Boards
Interconnection Carriers

State of the Art: PCB's

Revisio

Datum:

Seite:

PRINTED CIRCUIT BOARDS

01

4.11.2001

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Schematic Key for Multilayer and HDI-Technology Build-Ups

a	b	c	d	e	f	g + h + i
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04 322 FR4 105 L141.105 P18

columns and equal kind of positions are separated by "_". Equal prefixes in one column are reduced to one.

04_322_FR4_105_L141.105_p18

Layers	in μ	Material	Build-Up	Assembly		
Layer-1	105 μ	Copper	 (180 μ PrePreg-Type: 7628)			
	180 μ	Prepreg				
	180 μ	Prepreg				
	180 μ	Prepreg				
	180 μ	Prepreg				
Layer-2	105 μ	Copper				
	1410 μ	L-FR4				
Layer-3	105 μ	Copper				
	180 μ	Prepreg				
	180 μ	Prepreg				
	180 μ	Prepreg				
Layer-99	105 μ	Copper				
	180 μ	Prepreg				
	180 μ	Prepreg				

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